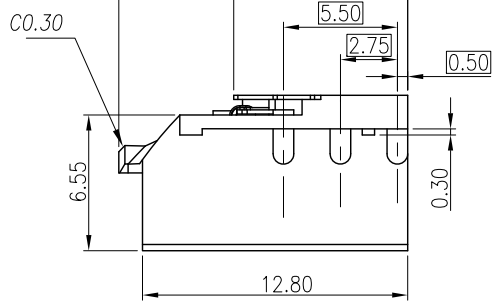
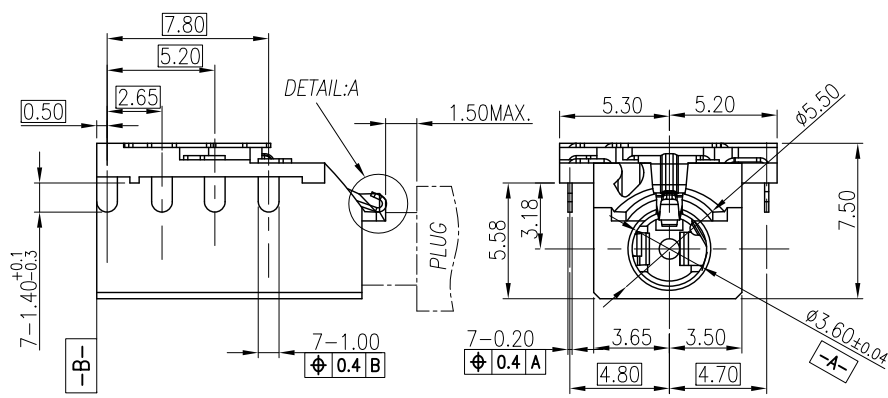
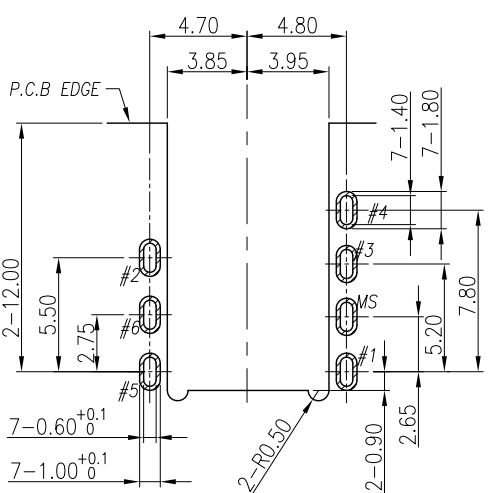


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO.: T140901-6A	Jie	2014.09.04

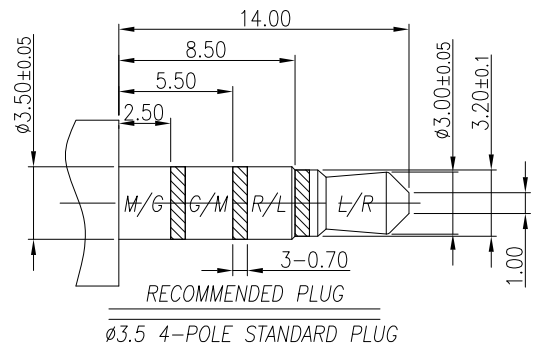


SPECIFICATIONS:

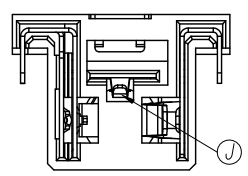
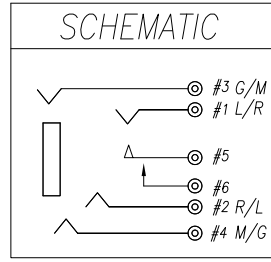
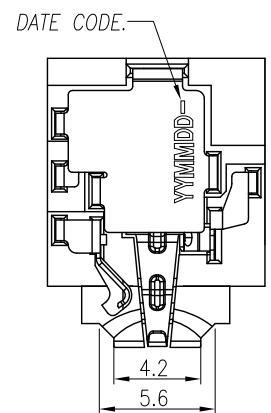
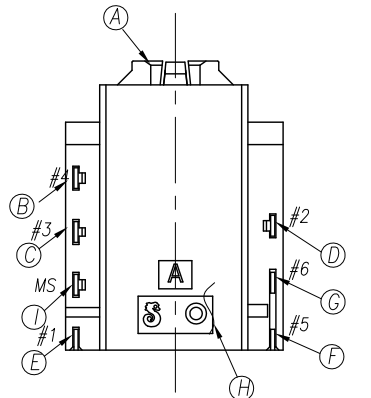
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500V DC .
- CONTACT RESISTANCE: 50mΩ MAX(INITIAL).
- INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
- LIFE TEST: 5,000 CYCLES.
- INSERTION FORCE: 0.3-3.0Kgf ,
- WITHDRAWAL FORCE: 0.3-3.0 Kgf,
- AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
- AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
- MARKING: MARK " ON TOP OF CONNECTOR.
- PACKING : TAPE & REEL.
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
- HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:



RECOMMENDED PCB LAYOUT
TOP VIEW ; TOL.±0.05



RECOMMENDED PLUG
Ø3.5 4-POLE STANDARD PLUG



DETAIL:A
SCALE:2:1

J	DUMMY	1	STAINLESS STEEL,0.20T	Ni 60u"Min.
I	SHELL	1	COPPER ALLOY, 0.2t	Ni 60u"Min.
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA; GOLD FLASH ON SOLDER AREA; ALL OVER 50u" Ni.
F	TRANSFER	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA; Matte Sn 80u" ON SOLDER AREA;
E	TIP	1	COPPER ALLOY, 0.2t	
D	RING-A	1	COPPER ALLOY, 0.2t	ALL OVER 50u" Ni.
C	EARTH	1	COPPER ALLOY, 0.2t	
B	RING-B	1	COPPER ALLOY, 0.2t	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

DECIMALS: ANGLES:
X :±0.5 X :±2°
X.X :±0.3 X.X :±1°
X.XX :±0.2

TITLE	3.5Ø PHONE JACK		
DWN	Jie	PART NO. 2SJ3095-048111F	
CHKD	Bruce	SCALE 4:1	UNIT: mm
APVD	Lussen	SIZE: A3	SHEET:1 OF 1 REV: A

CUSTOMER COPY